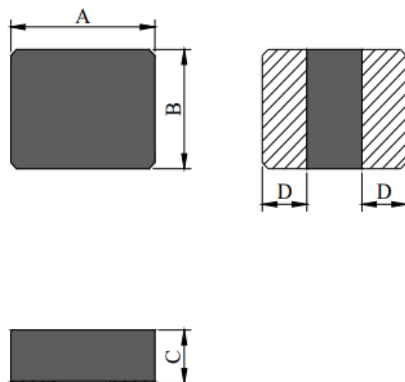


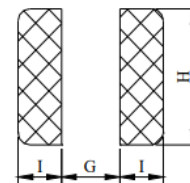
MMD201610-DCseries



SHAPE AND DIMENSIONS (mm)



RECOMMENDED PATTERN (mm)



Type	A	B	C	D	G	H	I
MMD201610	2.0±0.2	1.6±0.2	1.0Max.	0.7 ref.	0.5 ref.	1.8 ref.	0.8 ref.

APPLICATION

Laptop, Smartphone, LCD panel,
Bluetooth and other electronic devices

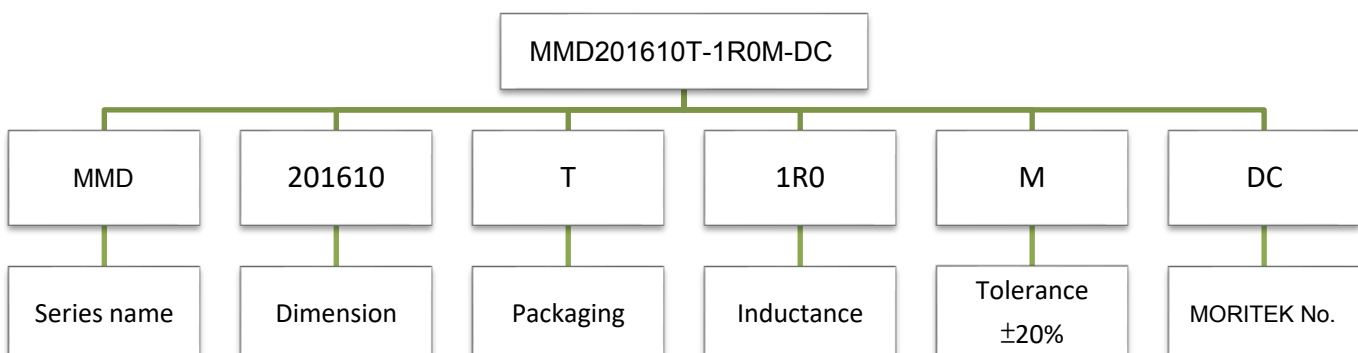
RATING

Operating Temperature : -55°C ~ +125°C
Storage Temperature : Under 40°C, Humidity < 75%

MATERIAL LIST

- a. Core : Alloy powder
- b. Wire : Enameled copper wire
- c. Terminal : Cu / Ni / Sn

PRODUCT IDENTIFICATION (ex.)



ELECTRICAL CHARACTERISTICS

Part No.	Inductance (uH)	Inductance tolerance	Test Frequency	DC Resistance (Ω)		Saturation current Isat(mA)		Temperature rise current Irms(mA)	
				Typ.	Max.	Typ.	Max.	Typ.	Max.
MMD201610T-R24M-DC	0.24	±20%	1MHz	0.012	0.019	8000	7400	6800	6200
MMD201610T-R33M-DC	0.33	±20%	1MHz	0.017	0.022	7000	6500	5700	5300
MMD201610T-R47M-DC	0.47	±20%	1MHz	0.022	0.025	6300	5500	5500	5000
MMD201610T-R68M-DC	0.68	±20%	1MHz	0.025	0.032	5200	4700	4600	4300
MMD201610T-1R0M-DC	1.0	±20%	1MHz	0.035	0.043	4600	4200	4500	4100
MMD201610T-1R5M-DC	1.5	±20%	1MHz	0.080	0.100	3200	2900	2600	2300
MMD201610T-2R2M-DC	2.2	±20%	1MHz	0.120	0.130	3000	2800	2500	2100
MMD201610T-3R3M-DC	3.3	±20%	1MHz	0.140	0.170	2300	2000	1700	1500
MMD201610T-4R7M-DC	4.7	±20%	1MHz	0.190	0.220	2000	1800	1600	1400
MMD201610T-100M-DC	10	±20%	1MHz	0.480	0.580	1400	1100	1000	700

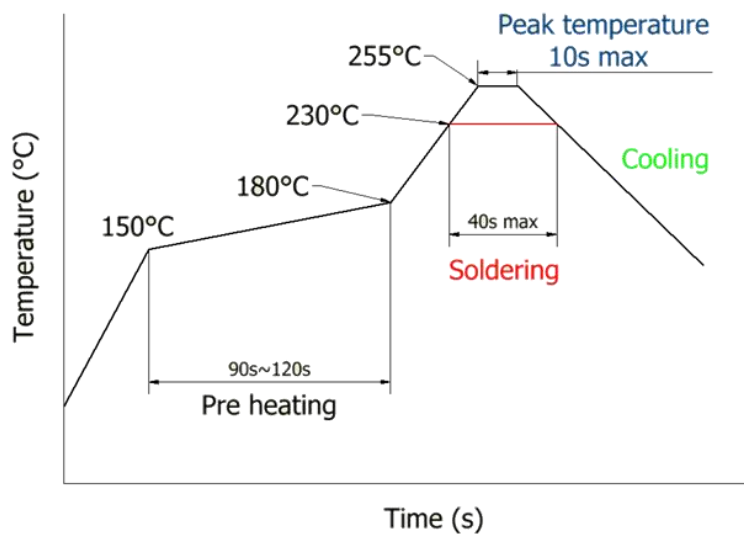
Note:

All test data is referenced to 25°C ambient

Isat base on $\Delta L / LOA=30$

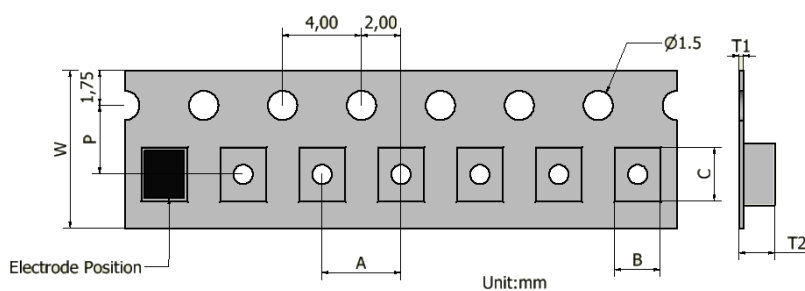
Irms base on Temp. rise 40

RECOMMENDED SOLDERING CONDITIONS



PACKAGE

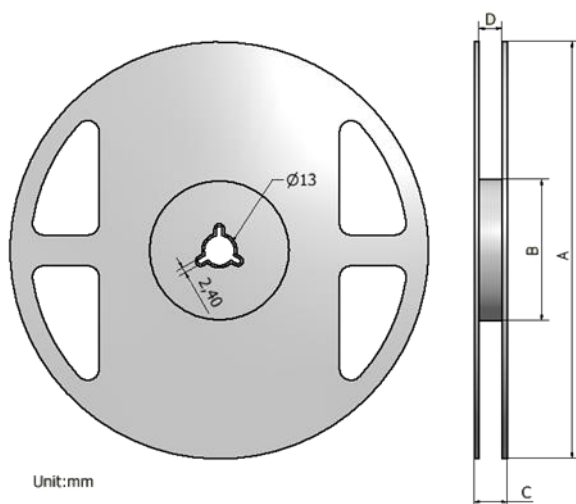
(1) Taping specifications



Type	W	P	A	B	C	T1	T2
MMD201610	8	3.5	4.0	1.85	2.45	0.23	1.2

(2) Reel specifications

Label



Molding Power Inductors
MMD201610T-□□□M-DC
3,000 PCS
Lot No. _____
MORITEK TECHNICAL CO., LTD.

Type	A	B	C	D	Q'ty/Reel
MMD201610	178	60	12	9	3000